

AG could bonding of said upper and lower semiconductor chips, and wherein bonding said upper and lower semiconductor chips includes arranging a die bonding material for bonding said upper and lower semiconductor chips to said first and second die pad.

IN THE ABSTRACT:

Replace the Abstract with:

ABSTRACT OF THE DISCLOSURE

AG could A semiconductor device and a manufacturing method for downsizing and densification achieved by reducing the thickness of the semiconductor device without an increase in area. Terminal electrodes are arranged, in plan view, outside a region where semiconductor chips are arranged. A lower semiconductor chip is placed overlapping in height the terminal electrodes, an upper semiconductor chip is placed above the lower semiconductor chip, wires connect the upper and lower semiconductor chips to the terminal electrodes, and an encapsulating resin encapsulates the upper and lower semiconductor chips and wires. The encapsulating resin has its bottom surface coplanar with the bottom surface of the terminal electrodes.